

# **DHG50X1200NA**

preliminary

 $V_{RRM} = 1200 V$ 

 $I_{FAV} = 2x \quad 25 A$ 

t<sub>rr</sub> = 200 ns

High Performance Fast Recovery Diode Low Loss and Soft Recovery Parallel legs

**Sonic Fast Recovery Diode** 

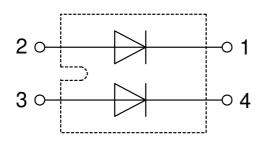
Part number

**DHG50X1200NA** 



Backside: Isolated





### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

# **Applications:**

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper
- internally DCB isolated

   Advanced power cycling

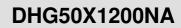
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IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified

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preliminary

Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V <sub>RSM</sub>	max. non-repetitive reverse blockii	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V <sub>RRM</sub>	max. repetitive reverse blocking vo	ltage	$T_{VJ} = 25^{\circ}C$			1200	V
IR	reverse current, drain current	V <sub>R</sub> = 1200 V	$T_{VJ} = 25^{\circ}C$			30	μΑ
		$V_{R} = 1200 \text{ V}$	$T_{VJ} = 125^{\circ}C$			0.5	mΑ
V <sub>F</sub>	forward voltage drop	I <sub>F</sub> = 25 A	$T_{VJ} = 25^{\circ}C$			2.11	V
		$I_F = 50 \text{ A}$				2.74	٧
		I <sub>F</sub> = 25 A	T <sub>VJ</sub> = 125°C			2.09	V
		$I_F = 50 \text{ A}$				2.88	٧
I <sub>FAV</sub>	average forward current	$T_{C} = 65^{\circ}C$	$T_{VJ} = 150$ °C			25	Α
		rectangular d = 0.5					i 
V <sub>F0</sub>	threshold voltage		T <sub>VJ</sub> = 150°C			1.23	٧
r <sub>F</sub>	slope resistance	ss calculation only				30	mΩ
R <sub>thJC</sub>	thermal resistance junction to case					1.2	K/W
R <sub>thCH</sub>	thermal resistance case to heatsin	k			0.1		K/W
P <sub>tot</sub>	total power dissipation		$T_{C} = 25^{\circ}C$			100	W
I <sub>FSM</sub>	max. forward surge current	$t = 10 \text{ ms}$ ; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			200	Α
C¹	junction capacitance	$V_R = 600  \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		11		pF
I <sub>RM</sub>	max. reverse recovery current		T <sub>VJ</sub> = 25 °C		23		Α
		$I_F = 30 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 125 ^{\circ}\text{C}$		30		Α
t <sub>rr</sub>	reverse recovery time	$I_F = 30 \text{ A}; V_R = 600 \text{ V}$ -di <sub>F</sub> /dt = 600 A/ $\mu$ s	$T_{VJ} = 25 ^{\circ}C$		200		ns
	)		$T_{VJ} = 125 ^{\circ}\text{C}$		350		ns



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Package	Package SOT-227B (minibloc)				Ratings			
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current	per terminal					100	Α
T <sub>VJ</sub>	virtual junction temperatu	ıre			-40		150	°C
Top	operation temperature				-40		125	°C
T <sub>stg</sub>	storage temperature				-40		150	°C
Weight						30		g
M <sub>D</sub>	mounting torque				1.1		1.5	Nm
$\mathbf{M}_{_{T}}$	terminal torque				1.1		1.5	Nm
d <sub>Spp/App</sub>	oroonago distanco on su	rface   etriking dietance through air	terminal to terminal	10.5	3.2			mm
$d_{\text{Spb/Apb}}$	creepage distance on surface   striking distance through		terminal to backside	8.6	6.8			mm
V <sub>ISOL</sub>	isolation voltage	t = 1 second	50/60 Hz, RMS; IsoL ≤ 1 mA		3000			V
		t = 1 minute			2500			V

# Product Marking Part Number Number 123456 Date Location Lot#

# Part description

D = Diode

H = Sonic Fast Recovery Diode

G = extreme fast

50 = Current Rating [A]

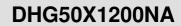
X = Parallel legs

1200 = Reverse Voltage [V]

NA = SOT-227B (minibloc)

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DHG50X1200NA	DHG50X1200NA	Tube	10	507766

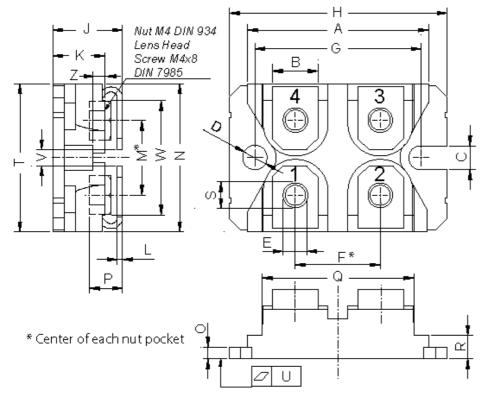
<b>Equivalent Circuits for Simulation</b>			* on die level	$T_{VJ} = 150^{\circ}C$
$I \rightarrow V_0$	)— <u>R</u> o	Fast Diode		
V <sub>0 max</sub>	threshold voltage	1.23		V
$R_{0max}$	slope resistance *	28		$m\Omega$



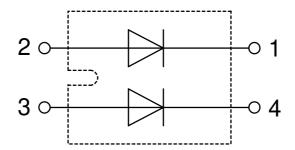


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# Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	31.50	31.88	1.240	1.255	
В	7.80	8.20	0.307	0.323	
С	4.09	4.29	0.161	0.169	
D	4.09	4.29	0.161	0.169	
Е	4.09	4.29	0.161	0.169	
F	14.91	15.11	0.587	0.595	
G	30.12	30.30	1.186	1.193	
Н	37.80	38.23	1.488	1.505	
J	11.68	12.22	0.460	0.481	
K	8.92	9.60	0.351	0.378	
L	0.74	0.84	0.029	0.033	
M	12.50	13.10	0.492	0.516	
N	25.15	25.42	0.990	1.001	
0	1.95	2.13	0.077	0.084	
Р	4.95	6.20	0.195	0.244	
Q	26.54	26.90	1.045	1.059	
R	3.94	4.42	0.155	0.167	
S	4.55	4.85	0.179	0.191	
Т	24.59	25.25	0.968	0.994	
U	-0.05	0.10	-0.002	0.004	
V	3.20	5.50	0.126	0.217	
W	19.81	21.08	0.780	0.830	
Ζ	2.50	2.70	0.098	0.106	





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# **Fast Diode**

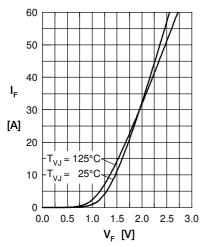


Fig. 1 Typ. Forward current versus V<sub>F</sub>

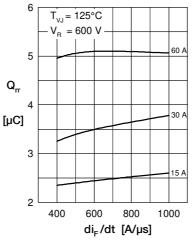


Fig. 2 Typ. reverse recov. charge  $Q_{rr}$  versus di/dt

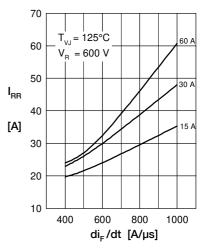
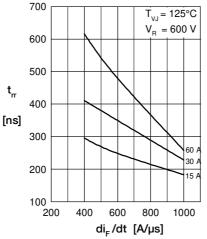


Fig. 3 Typ. peak reverse current  $I_{\rm RM}$  versus di/dt



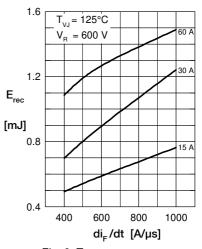


Fig. 6 Typ. recovery energy  $E_{\rm rec}$  versus di/dt

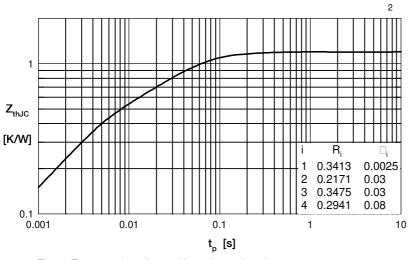


Fig. 7 Typ. transient thermal impedance junction to case